

SCOPE OF ACCREDITATION

Electronics - Printed Board Assemblies

MB elettronica S.r.l.
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Cortona, 52044
Italy

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)

- 03–Company Information (mandatory)
- 04– General (mandatory)
- 05– Outsourced Processes (mandatory)
- 06– Process Control (mandatory)
- 07– Visual Acuity (mandatory)
- 08– Customer Data (mandatory)
- 09– Electrostatic Discharge (ESD) (mandatory)
- 10– Material Management (mandatory)
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General (mandatory)
- 13.2– In–Process Verification / Inspection: Visual (mandatory)
- 13.3– In–Process Verification / Inspection: AOI
- 13.4– In–Process Verification / Inspection: X–Ray
- 15– Cleanliness
- 16– Final Inspection (mandatory)
- 17– Rework (mandatory)

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 03– General (mandatory)
- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General (mandatory)
- 05.2– Part Placement: Manual
- 06– Gold Removal
- 07– Build Through / Build Short

08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

05– Selective Soldering

AC7120/4 Rev A - Surface Mount Technology (to be used on audits on/after 3 March 2019)

03– Preparation

04– Stencil Printing (mandatory)

05– Automated Part Placement (mandatory)

06– Reflow Soldering (mandatory)

AC7120/5 - Mixed Metallurgy for BGAs (to be used on audits on/after 9 April 2017)

03– Lead–Free Control Plan (LFCP) (mandatory)

04– Qualification for Assemblies Containing BGAS (mandatory)

AC7120/6 - Lead Free Soldering (to be used on audits on/after 9 April 2017)

03– Lead–Free Control Plan (LFCP) (mandatory)

04– Process Control (mandatory)

05– Training (mandatory)

AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits BEFORE 05-Nov-2023)

04– Material (mandatory)

05– Material and Equipment Compatibility (mandatory)

06– Preparation / Cleaning (mandatory)

07– Application / Drying / Curing (mandatory)

08– Thickness (mandatory)

09– Inspection (mandatory)

10– Rework (mandatory)

11– Training (mandatory)

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

04– General

AC7120/12 - Nadcap Audit Criteria for Depaneling (to be used on audits on/after 30 June 2019)

03.1– Inspection (mandatory)

04– Mechanical Router Process

12– Preservation and Packing of Depaneled Images (mandatory)